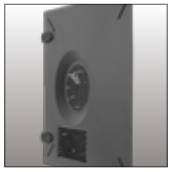
Z 670

mATX *chassis*

Features

TAC 2.0 Thermal Solution

Qualified for TAC 2.0, a mass ventilation hole side panel design strengthens thermal efficiency and cools down the entire system.



Side Panel Clip

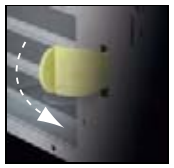
The patented tool free installation side panel clip.

Cooling Fan

Optional 9cm auxiliary cooling fan at rear panel for better system cooling.

Tool Free Installation and Easy Maintenance

Screw-less front panel, drive bays & I/O slots.



Folded Edge

For safety installation. No sharp edges, debris.

Stamped Motherboard Support

No M/B standoffs installation required, for faster M/B installation.

CASE SIZE	Mini Tower Chassis
EXTERNAL DRIVE BAY	5.25" x 2, 3.5" x 1
INTERNAL DRIVE BAY	3.5" x 2, 2.5" x 1
FRONT PORTS	USB2.0 x 2 , HD Audio
DIMENSIONS(HxWxD)	363 x 180 x 370mm
w/o Front Panel	14.3" x 7.1" x 14.6"
M/B	Micro-ATX
I/O EXPANSION SLOTS	PCI-E / PCI / AGP Expansion Slot x 4
POWER SUPPLY	ATX 12V Form Factor, PS II
THERMAL SOLUTION	Intel Certified TAC 2.0
COOLING FAN	8 or 9cm Rear Fan
SAFETY	Meets RoHS, CE and FCC Class B Requirements.
SECURITY	Padlock Loop for Padlock / Kensington Slot
OPTIONAL	8 or 9cm Rear Fan / eSATA / Chassis Intrusion Switch
	USB 3.0 x 2 / 3.5" to 2.5" HDD / SSD Bracket

Specification